

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6126xxxx7R-G  
Typical Mass: 1 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.047	Silicon	47200	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	0.135	Nickel	135000	7440-02-0
	0.003	Gold	3000	7440-57-5
Die attach	0.004	Epoxy Resin	4400	—
	0.003	Acrylic Resin	2600	—
Bonding wire	0.023	Gold	22700	7440-57-5
Resin	0.475	Silica	475000	60676-86-0
	0.086	Epoxy Resin	86400	—
	0.086	Phenol Resin	86400	—
	0.118	Metal hydroxide	117800	—
	0.020	Silica (crystal)	19600	14808-60-7

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."